MA3X152D (MA152WA), MA3X152E (MA152WK)

Silicon epitaxial planar type

For high-speed switching circuits

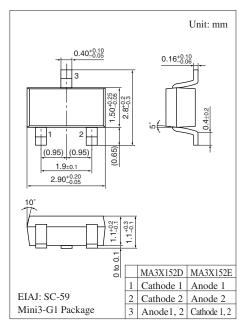
■ Features

- Short reverse recovery time t_{rr}
- Small terminal capacitance, C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Maximum peak reverse voltage		V_{RM}	80	V
Forward current	Single	I_{F}	100	mA
	Double		150	
Peak forward	Single	I_{FM}	225	mA
current	Double		340	
Non-repetitive peak	Single	I_{FSM}	500	mA
forward surge current *	Double		750	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C

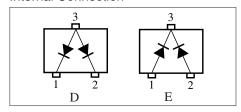
Note) *: t = 1 s



Marking Symbol

MA3X152D: MO
 MA3X152E: MU

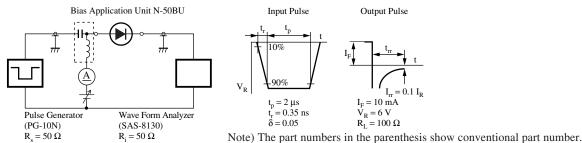
Internal Connection



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V_{F}	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage		V_R	$I_R = 100 \mu A$	80			V
Reverse current		I_R	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	MA3X152D	C _t	$V_R = 0 V, f = 1 MHz$			15	pF
	MA3X152E					2	
Reverse recovery time *	MA3X152D	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
	MA3X152E		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$			3	

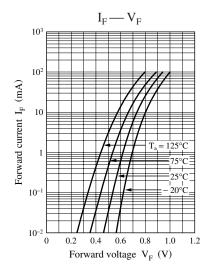
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.
 - 2. Absolute frequency of input and output is 100 MHz.
 - 3. *: t_{rr} measurement circuit

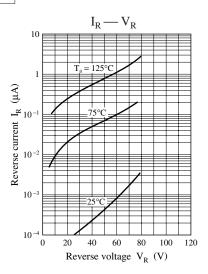


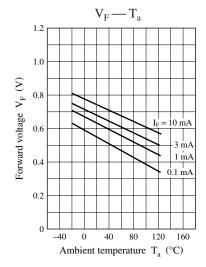
Publication date: November 2003 SKF00033CED 1

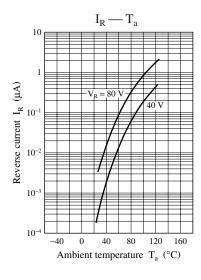
Panasonic

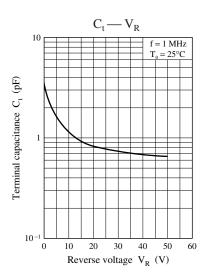
Characteristics chart of MA3X152D







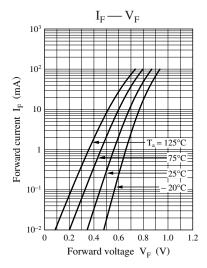


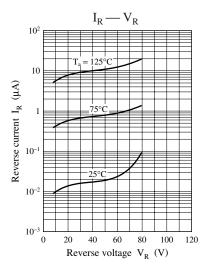


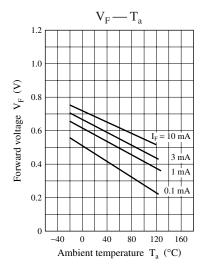
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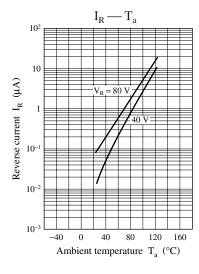
Panasonic

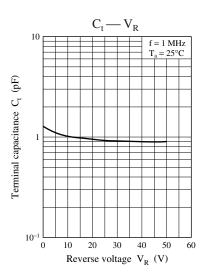
Characteristics chart of MA3X152E











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